SCHS322 - JANUARY 2003

 Inputs Are TTL-Voltage Compatible Speed of Bipolar F, AS, and S, With Significantly Reduced Power Consumption 	CD54ACT86 F PACKAGE CD74ACT86 E OR M PACKAGE (TOP VIEW)
Balanced Propagation Delays	1A [1 14] V _{CC}
±24-mA Output Drive Current	1B 2 13 4B
 Fanout to 15 F Devices 	
 SCR-Latchup-Resistant CMOS Process and 	
Circuit Design	2B 5 10 3B
Exceeds 2-kV ESD Protection Per	2Y 6 9 3A
MIL-STD-883, Method 3015	GND [7 8] 3Y

description/ordering information

The 'ACT86 devices are quadruple 2-input exclusive-OR gates. These devices perform the Boolean function $Y = A \oplus B$ or $Y = \overline{AB} + A\overline{B}$ in positive logic.

A common application is as a true/complement element. If one of the inputs is low, the other input is reproduced in true form at the output. If one of the inputs is high, the signal on the other input is reproduced inverted at the output.

T _A	PACKA	GE†	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – E	Tube	CD74ACT86E	CD74ACT86E
–55°C to 125°C	SOIC – M	Tube	CD74ACT86M	ACT86M
-55 C 10 125 C	301C - M	Tape and reel	CD74ACT86M96	ACTOON
	CDIP – F	Tube	CD54ACT86F3A	CD54ACT86F3A

ORDERING INFORMATION

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE
(each gate)

INP	UTS	OUTPUT				
Α	В	Y				
L	L	L				
L	н	Н				
н	L	Н				
Н	Н	L				



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

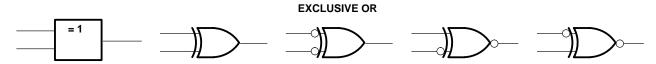


Copyright © 2003, Texas Instruments Incorporated On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

SCHS322 – JANUARY 2003

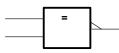
exclusive-OR logic

An exclusive-OR gate has many applications, some of which can be represented better by alternative logic symbols.



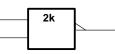
These are five equivalent exclusive-OR symbols valid for an CD74AC86 gate in positive logic; negation may be shown at any two ports.

LOGIC-IDENTITY ELEMENT



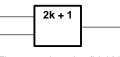
The output is active (low) if all inputs stand at the same logic level (i.e., A = B).

EVEN-PARITY ELEMENT



The output is active (low) if an even number of inputs (i.e., 0 or 2) are active.

ODD-PARITY ELEMENT



The output is active (high) if an odd number of inputs (i.e., only 1 of the 2) are active.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V _{CC}	0.5 V to 6 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) (see Note 1)	±20 mA
Output clamp current, I_{OK} (V _O < 0 or V _O > V _{CC}) (see Note 1)	±50 mA
Continuous output current, $I_O (V_O = 0 \text{ to } V_{CC})$	±50 mA
Continuous current through V _{CC} or GND	±100 mA
Package thermal impedance, θ_{JA} (see Note 2): E package	80°C/W
M package	86°C/W
Storage temperature range, T _{stg}	. −65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

		T _A = 2	25°C	–55°C to 125°C		–40° 85°	UNIT	
		MIN	MAX	MIN	MAX	MIN	MAX	
VCC	Supply voltage	4.5	5.5	4.5	5.5	4.5	5.5	V
VIH	High-level input voltage	2		2		2		V
VIL	Low-level input voltage		0.8		0.8		0.8	V
VI	Input voltage	0	VCC	0	VCC	0	VCC	V
Vo	Output voltage	0	VCC	0	VCC	0	VCC	V
ЮН	High-level output current		-24		-24		-24	mA
IOL	Low-level output current		24		24		24	mA
$\Delta t/\Delta v$	Input transition rise or fall rate		10		10		10	ns/V

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



SCHS322 - JANUARY 2003

PARAMETER	TEST CONDITIONS		Vcc	T _A = 25°C		–55°C to 125°C		–40°C to 85°C		UNIT	
			MIN	MAX	MIN	MAX	MIN	MAX			
		I _{OH} = -50 μA	4.5 V	4.4		4.4		4.4			
	$\lambda = \lambda = 0$	I _{OH} = -24 mA	4.5 V	3.94		3.7		3.8		V	
VOH	$V_{I} = V_{IH} \text{ or } V_{IL}$	I _{OH} = -50 mA†	5.5 V			3.85				V	
		I _{OH} = -75 mA†	5.5 V					3.85			
		I _{OL} = 50 μA	4.5 V		0.1		0.1		0.1		
No.	VI = VIH or VIL	I _{OL} = 24 mA	4.5 V		0.36		0.5		0.44	v	
VOL		$I_{OL} = 50 \text{ mA}^{\dagger}$	5.5 V				1.65				
		I _{OL} = 75 mA [†]	5.5 V						1.65		
lj	$V_{I} = V_{CC} \text{ or } GND$		5.5 V		±0.1		±1		±1	μA	
ICC	$V_I = V_{CC}$ or GND,	I ^O = 0	5.5 V		4		80		40	μA	
∆I _{CC} ‡	$V_{I} = V_{CC} - 2.1 V$		4.5 V to 5.5 V		2.4		3		2.8	mA	
Ci					10		10		10	pF	

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

⁺ Test one output at a time, not exceeding 1-second duration. Measurement is made by forcing indicated current and measuring voltage to minimize power dissipation. Test verifies a minimum 50-Ω transmission-line drive capability at 85°C and 75-Ω transmission-line drive capability at 125°C.

[‡]Additional quiescent supply current per input pin, TTL inputs high, 1 unit load

ACT INPUT LOAD TABLE

INPUT	UNIT LOAD
All	0.48

Unit Load is ΔI_{CC} limit specified in electrical characteristics table (e.g., 2.4 mA at 25°C).

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

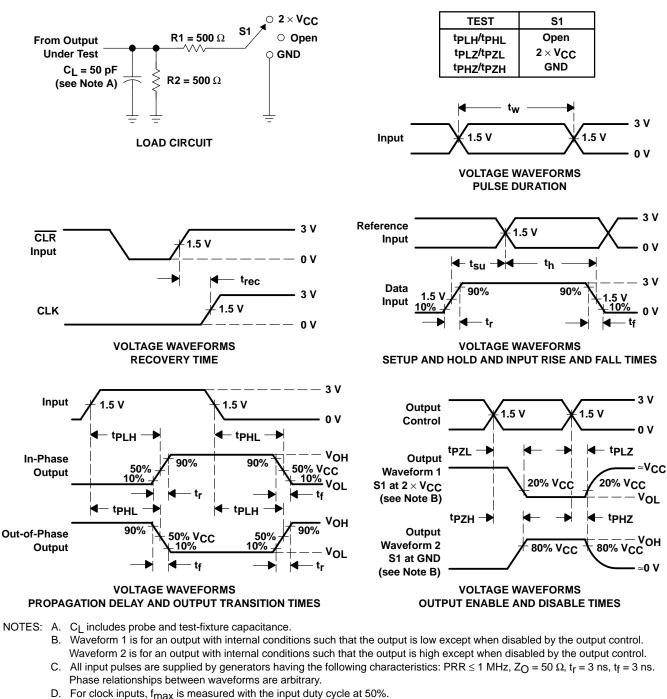
PARAMETER	FROM (INPUT)	TO -55° (OUTPUT) -25			–40° 85°		UNIT
	(INFOT)	(6611 61)	MIN	MAX	MIN	MAX	
^t PLH	A or B	Y	3.7	14.6	3.8	13.3	
^t PHL	AOIB	Ť	3.7	14.6	3.8	13.3	ns

operating characteristics, $V_{CC} = 5 V$, $T_A = 25^{\circ}C$

	PARAMETER	TYP	UNIT
C _{pd}	Power dissipation capacitance	57	pF

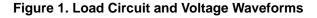


SCHS322 – JANUARY 2003



PARAMETER MEASUREMENT INFORMATION

- E. The outputs are measured one at a time with one input transition per measurement.
- F. tpLH and tpHL are the same as tpd.
- G. t_{P7I} and t_{P7H} are the same as t_{en} .
- H. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
- I. All parameters and waveforms are not applicable to all devices.





IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products		Applications	
Amplifiers	amplifier.ti.com	Audio	www.ti.com/audio
Data Converters	dataconverter.ti.com	Automotive	www.ti.com/automotive
DSP	dsp.ti.com	Broadband	www.ti.com/broadband
Interface	interface.ti.com	Digital Control	www.ti.com/digitalcontrol
Logic	logic.ti.com	Military	www.ti.com/military
Power Mgmt	power.ti.com	Optical Networking	www.ti.com/opticalnetwork
Microcontrollers	microcontroller.ti.com	Security	www.ti.com/security
Low Power Wireless	www.ti.com/lpw	Telephony	www.ti.com/telephony
		Video & Imaging	www.ti.com/video
		Wireless	www.ti.com/wireless

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2007, Texas Instruments Incorporated

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
CD54ACT86F3A	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
CD74ACT86E	ACTIVE	PDIP	Ν	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CD74ACT86EE4	ACTIVE	PDIP	Ν	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CD74ACT86M	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74ACT86M96	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74ACT86M96E4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74ACT86M96G4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74ACT86ME4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74ACT86MG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details. **TBD**: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered

at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. **Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer:The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF CD54ACT86, CD74ACT86 :

• Enhanced Product: CD74ACT86-EP

PACKAGE OPTION ADDENDUM



18-Sep-2008

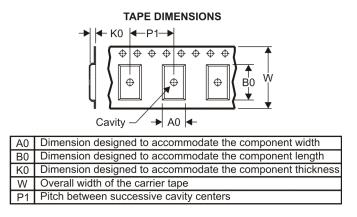
NOTE: Qualified Version Definitions:

• Enhanced Product - Supports Defense, Aerospace and Medical Applications

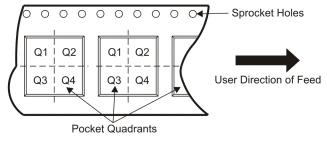
TEXAS INSTRUMENTS www.ti.com

TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All	dimensions	are	nominal
------	------------	-----	---------

Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD74ACT86M96	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1



PACKAGE MATERIALS INFORMATION

11-Mar-2008



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CD74ACT86M96	SOIC	D	14	2500	346.0	346.0	33.0

J (R-GDIP-T**) 14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE

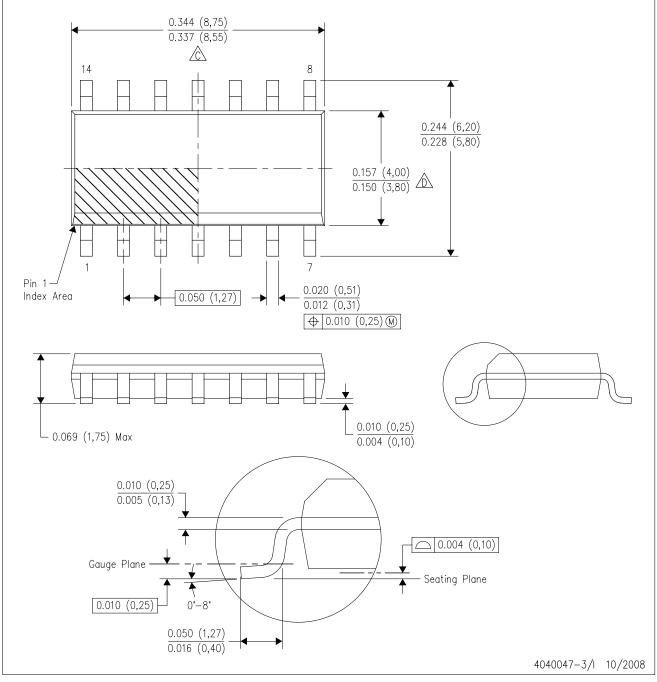


NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
- Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
- E. Reference JEDEC MS-012 variation AB.



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.

